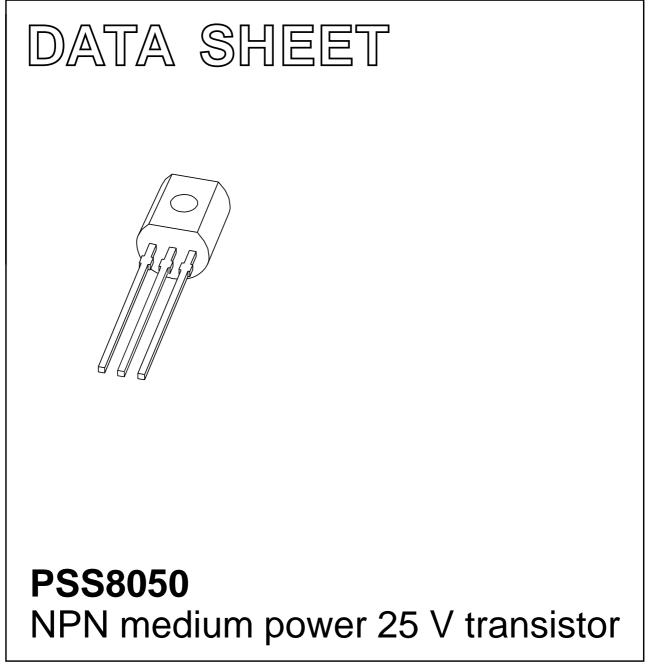
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2002 Nov 18 2004 Aug 10



### FEATURES

- High total power dissipation
- High current capability.

### APPLICATIONS

- · Medium power switching and muting
- Amplification
- Portable radio output amplifier (class-B, push-pull).

#### DESCRIPTION

NPN transistor in a SOT54 (TO-92) plastic package. PNP complement: PSS8550.

#### MARKING

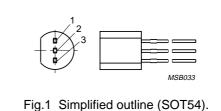
TYPE NUMBER	MARKING CODE		
PSS8050C	S8050C		
PSS8050D	S8050D		

### QUICK REFERENCE DATA

SYMBOL PARAMETER		MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	25	V
Ι <sub>C</sub>	collector current (DC)	1.5	A

#### PINNING

PIN	DESCRIPTION	
1	collector	
2	base	
3	emitter	



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.	UNIT	
V <sub>CBO</sub>	collector-base voltage	open emitter	-	40	V	
V <sub>CEO</sub>	collector-emitter voltage	open base	_	25	V	
V <sub>EBO</sub>	emitter-base voltage	open collector	-	6	V	
I <sub>C</sub>	collector current (DC)		-	1.5	A	
I <sub>CM</sub>	peak collector current		-	2	А	
I <sub>B</sub>	base current (DC)		-	300	mA	
I <sub>BM</sub>	peak base current		-	1	A	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	850	mW	
		$T_{amb} \le 25 \ ^{\circ}C$ ; note 2	-	900	mW	
		$T_{amb} \le 25 \ ^{\circ}C$ ; note 3	-	1	W	
T <sub>stg</sub>	storage temperature		-65	+150	°C	
Tj	junction temperature		-	150	°C	
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C	

#### Notes

- 1. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.
- 3. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint. Operated under pulsed conditions: pulse width  $t_p \le 1$  s; duty cycle  $\delta \le 0.75\%$ .

### PSS8050

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air; note 1	147	K/W
		in free air; note 2	139	K/W
		in free air; note 3	125	K/W

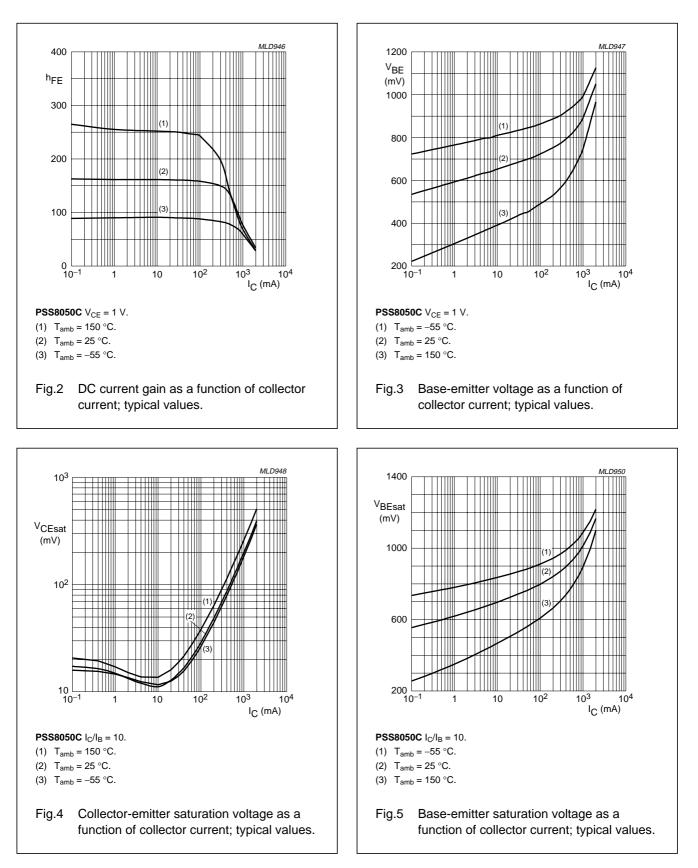
#### Notes

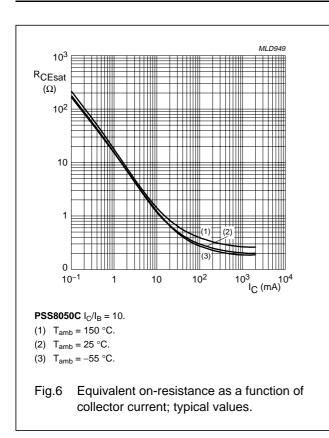
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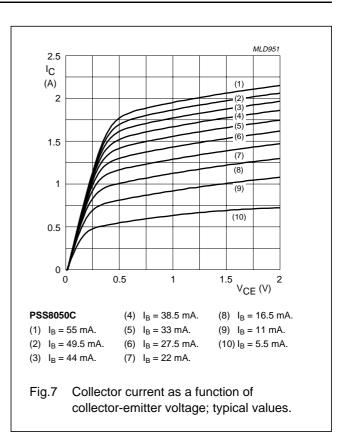
### CHARACTERISTICS

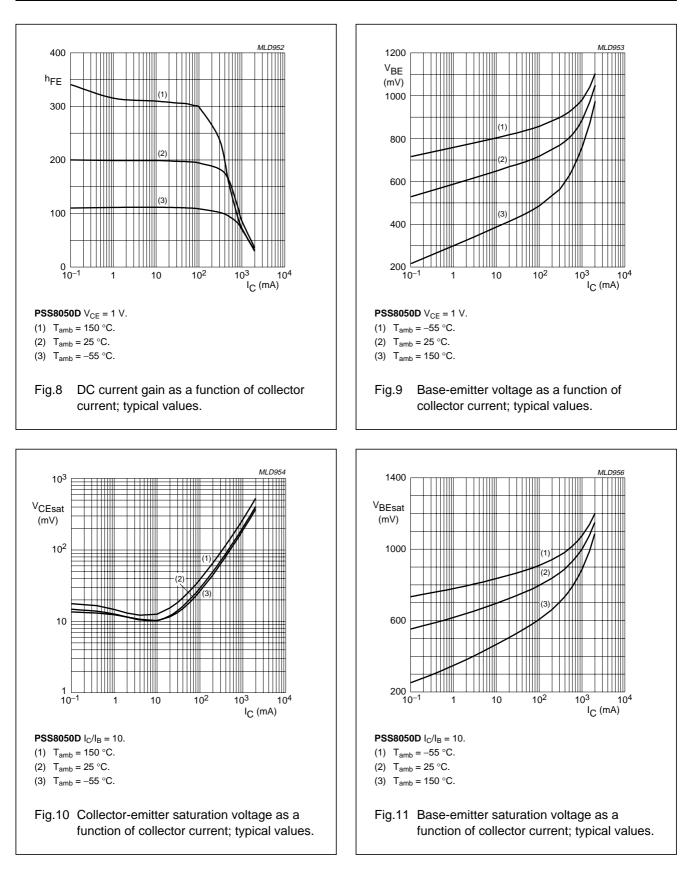
 $T_{amb}$  = 25 °C unless otherwise specified.

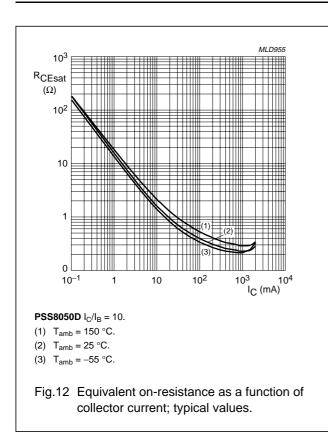
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 35 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA
		$V_{CB} = 35 \text{ V}; \text{ I}_{E} = 0; \text{ T}_{amb} = 150 ^{\circ}\text{C}$	-	-	50	μA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = 25 \text{ V}; \text{ I}_{B} = 0$	-	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 6 V; I_{C} = 0$	-	_	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 1 V	45	-	-	
		I <sub>C</sub> = 800 mA; V <sub>CE</sub> = 1 V	40	-	-	
	DC current gain	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 1 V				
	PSS8050C		120	-	200	
	PSS8050D		160	-	300	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 800 mA; I <sub>B</sub> = 80 mA	-	165	500	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 800 mA; I <sub>B</sub> = 80 mA	-	_	1.2	V
V <sub>BEon</sub>	base-emitter turn-on voltage	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 1 V	_	_	1	V
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 50 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	100	-	-	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = 10 \text{ V}; \text{ I}_{E} = \text{i}_{e} = 0; \text{ f} = 1 \text{ MHz}$	_	_	10	pF

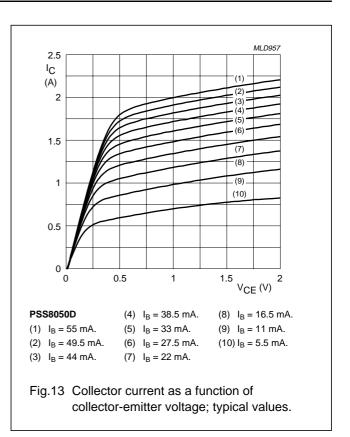




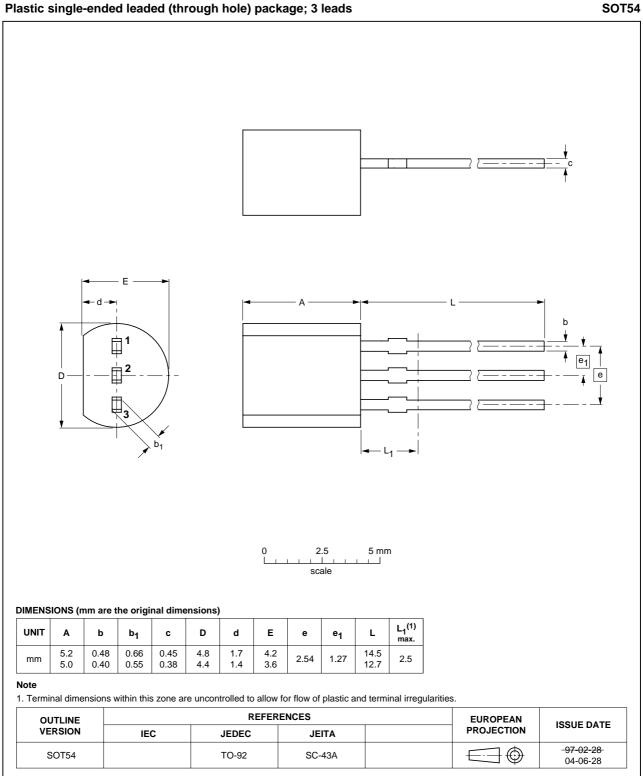








### PACKAGE OUTLINE



PSS8050

### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
1	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### DEFINITIONS

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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